

Material Composition Specification

SOT-883L Case

Pb (lead)-free plating



Device average mass **0.75 mg**

Fluctuation margin **+/-10%**

| Component | Material | Material | | Substance | CAS No. | Substance | | |
|---------------|--------------|----------|------|-------------|-------------|-----------|--------|--------|
| | | (%wt) | (mg) | | | (%wt) | (mg) | (ppm) |
| active device | doped Si | 2.70% | 0.02 | Si | 7440-21-3 | 2.70% | 0.0203 | 27000 |
| bond wire | gold | 0.83% | 0.01 | Au | 7440-57-5 | 0.83% | 0.0062 | 8300 |
| leadframe | copper alloy | 44.62% | 0.33 | Cu | 7440-50-8 | 44.62% | 0.3347 | 446200 |
| die attach | silver epoxy | 2.75% | 0.02 | Ag | 7440-22-4 | 1.94% | 0.0145 | 19350 |
| | | | | epoxy resin | Proprietary | 0.82% | 0.0061 | 8150 |
| encapsulation | EMC | 47.35% | 0.36 | silica | 7631-86-9 | 44.45% | 0.3334 | 444500 |
| | | | | epoxy resin | Proprietary | 2.80% | 0.0210 | 28000 |
| | | | | carbon | 1333-86-4 | 0.10% | 0.0008 | 1000 |
| plating | NiPdAu | 1.75% | 0.01 | Ni | 7440-02-0 | 1.69% | 0.0127 | 16930 |
| | | | | Pd | 7440-05-3 | 0.05% | 0.0004 | 500 |
| | | | | Au | 7440-57-5 | 0.01% | 0.0001 | 70 |

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.